Single Inverter with Schmitt-Trigger Input

The MC74HC1G14 is a high speed CMOS inverter with Schmitt-Trigger input fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer output which provides high noise immunity and stable output.

The MC74HC1G14 output drive current is 1/2 compared to MC74HC series.

- High Speed: $t_{PD} = 7.0 \text{ ns (Typ)}$ at $V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1.0 \mu A$ (Max) at $T_A = 25 ^{\circ}C$
- High Noise Immunity
- Balanced Propagation Delays (t_{PLH} = t_{PHL})
- Symmetrical Output Impedance ($I_{OH} = I_{OL} = 2.0 \text{ mA}$)
- Chip Complexity: FET = 101

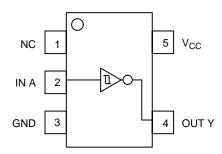


Figure 1. Pinout (Top View)

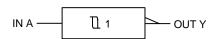
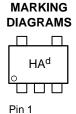


Figure 2. Logic Symbol



http://onsemi.com







SOT23-5/TSOP-5/SC59-5 DT SUFFIX CASE 483



d = Date Code

	PIN ASSIGNMENT				
1	NC				
2	IN A				
3	GND				
4	OUT Y				
5	V _{CC}				

FUNCTION TABLE

Inputs	Outputs
L	Н
Н	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol		Parameter	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage	-0.5 to $V_{CC} + 0.5$	V	
V _{OUT}	DC Output Voltage		-0.5 to $V_{CC} + 0.5$	V
I _{IK}	DC Input Diode Current		±20	mA
I _{OK}	DC Output Diode Current		±20	mA
I _{OUT}	DC Output Sink Current	± 12.5	mA	
I _{CC}	DC Supply Current per Supply Pin	±25	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1 mm from Case	260	°C	
TJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance	SC70-5/SC-88A/SOT-353 (Note 1) SOT23-5/TSOP-5/SC59-5	350 230	°C/W
P _D	Power Dissipation in Still Air at 85°C	SC70-5/SC-88A/SOT-353 SOT23-5/TSOP-5/SC59-5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	>2000 >200 N/A	V
I _{LATCH-UP}	Latch-Up Performance	Above V _{CC} and Below GND at 125°C (Note 5)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 20 ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	DC Supply Voltage		2.0	6.0	V
V _{IN}	DC Input Voltage		0.0	V _{CC}	V
V _{OUT}	DC Output Voltage		0.0	V _{CC}	V
T _A	Operating Temperature Range		- 55	+ 125	°C
t _r , t _f	Input Rise and Fall Time	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	-	No Limit No Limit	ns/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

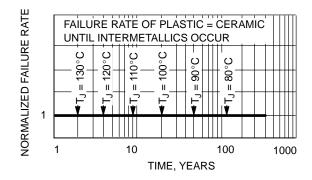


Figure 3. Failure Rate vs. Time Junction Temperature

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	٦	Γ _A = 25°(;	T _A ≤	85°C	-55°C ≤ 1	T _A ≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{T+}	Positive–Going Input Threshold Voltage	$V_{OUT} = 0.1 \text{ V}$ $ I_{OUT} \le 20 \mu\text{A}$	2.0 3.0 4.5 6.0	1.00 1.50 2.30 3.00	1.34 2.02 2.97 3.93	1.50 2.5 3.15 4.20	0.95 1.45 2.25 2.95	1.60 2.60 3.15 4.20	0.90 1.40 2.20 2.90	1.60 2.60 3.15 4.20	٧
V _T -	Negative-Going Input Threshold Voltage	$V_{OUT} = V_{CC} - 0.1$ V $ I_{OUT} \le 20 \mu A$	2.0 3.0 4.5 6.0	0.55 1.0 1.75 2.65	0.86 1.44 2.28 3.14	1.15 1.80 2.75 3.65	0.55 1.0 1.75 2.65	1.20 1.85 2.8 3.7	0.55 1.0 1.75 2.65	1.25 1.90 2.85 3.75	V
V _H	Hysteresis Voltage	$V_{OUT} = 0.1 \text{ V or}$ $V_{OUT} = V_{CC} - 0.1$ V $ I_{OUT} \le 20 \mu\text{A}$	2.0 3.0 4.5 6.0	0.20 0.25 0.30 0.40	0.478 0.584 0.686 0.790	0.8 0.95 1.1 1.25	0.20 0.25 0.30 0.40	0.8 0.55 1.1 1.5	0.20 0.25 0.30 0.40	0.8 0.95 1.1 1.25	V
V _{OH}	Minimum High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -20 \mu\text{A}$	2.0 3.0 4.5 6.0	1.9 2.9 4.4 5.9	2.0 3.0 4.5 6.0		1.9 2.9 4.4 5.9		1.9 2.9 4.4 5.9		٧
		$\begin{aligned} V_{IN} &\leq V_T - Min \\ I_{OH} &= -2 \text{ mA} \\ I_{OH} &= -2.6 \text{ mA} \end{aligned}$	4.5 6.0	4.18 5.68	4.31 5.80		4.13 5.63		4.08 5.58		
V _{OL}	Maximum Low-Level Output Voltage	$V_{IN} \ge V_T + Max$ $I_{OL} = 20 \mu A$	2.0 3.0 4.5 6.0		0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1	V
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 2$ mA $I_{OL} = 2.6$ mA	4.5 6.0		0.17 0.18	0.26 0.26		0.33 0.33		0.40 0.40	
I _{IN}	Maximum Input Leakage Current	$V_{IN} = 6.0 \text{ V or GND}$	6.0			±0.1		±1.0		±1.0	μΑ
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	6.0			1.0		10		40	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 6.0 \text{ ns}$)

				$T_A = 25^{\circ}C$		$T_A \leq 85^{\circ}C$		$-55^{\circ}C \leq T_{A} \leq 125^{\circ}C$			
Symbol	Parameter	Test Cor	nditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Maximum	V _{CC} = 5.0 V	C _L = 15 pF		3.5	15		20		25	ns
t _{PHL}	Propagation Delay, Input A or B to \(\overline{Y}\)	V _{CC} = 2.0 V V _{CC} = 3.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	C _L = 50 pF		19 10.5 7.5 6.5	100 27 20 17		125 35 25 21		155 90 35 26	
t _{TLH} ,	Output Transition	V _{CC} = 5.0 V	C _L = 15 pF		3	10		15		20	ns
^t ⊤HL	Time	V _{CC} = 2.0 V V _{CC} = 3.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	C _L = 50 pF		25 16 11 9	125 35 25 21		155 45 31 26		200 60 38 32	
C _{IN}	Maximum Input Capacitance				5	10		10		10	pF
							Туріс	al @ 25	°C, V _{CC} = 5.0	V	
C_{PD}	Power Dissipation Capacitance (Note 6)								10		pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

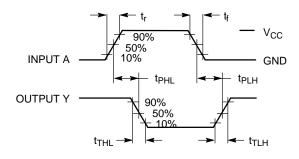
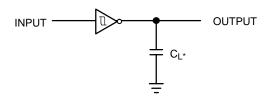


Figure 4. Switching Waveforms



*Includes all probe and jig capacitance. A 1–MHz square input wave is recommended for propagation delay tests.

Figure 5. Test Circuit

DEVICE ORDERING INFORMATION

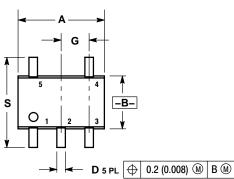
			Device Nome					
Device Order Number	Logic Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape and Reel Suffix	Package Type	Tape and Reel Size†
MC74HC1G14DFT1	МС	74	HC1G	14	DF	T1	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit
MC74HC1G14DFT2	МС	74	HC1G	14	DF	T2	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit
MC74HC1G14DTT1	MC	74	HC1G	14	DT	T1	SOT23-5/TSOP-5/ SC59-5	178 mm (7 in) 3000 Unit

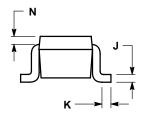
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC70-5/SC-88A/SOT-353 **DF SUFFIX**

5-LEAD PACKAGE CASE 419A-02 ISSUE G





- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

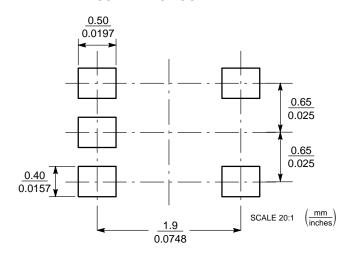
 2. CONTROLLING DIMENSION: INCH.

 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	REF	0.20	REF
S	0.079	0.087	2 00	2 20

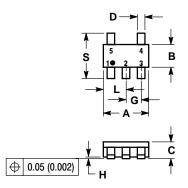
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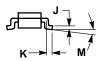


PACKAGE DIMENSIONS

SOT23-5/TSOP-5/SC59-5 **DT SUFFIX**

5-LEAD PACKAGE CASE 483-01 ISSUE C



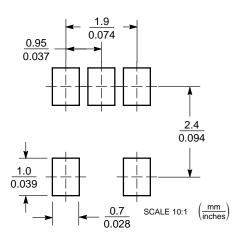


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- ANSI 114-3M, 1992.
 CONTROLLING DIMENSION: MILLIMETER.
 MAXIMUM LEAD THICKNESS INCLUDES
 LEAD FINISH THICKNESS. MINIMUM LEAD
 THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- A AND B DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.1142	0.1220	
В	1.30	1.70	0.0512	0.0669	
С	0.90	1.10	0.0354	0.0433	
D	0.25	0.50	0.0098	0.0197	
G	0.85	1.05	0.0335	0.0413	
Н	0.013	0.100	0.0005	0.0040	
J	0.10	0.26	0.0040	0.0102	
K	0.20	0.60	0.0079	0.0236	
L	1.25	1.55	0.0493	0.0610	
М	0	10	0	10	
S	2.50	3.00	0.0985	0.1181	

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